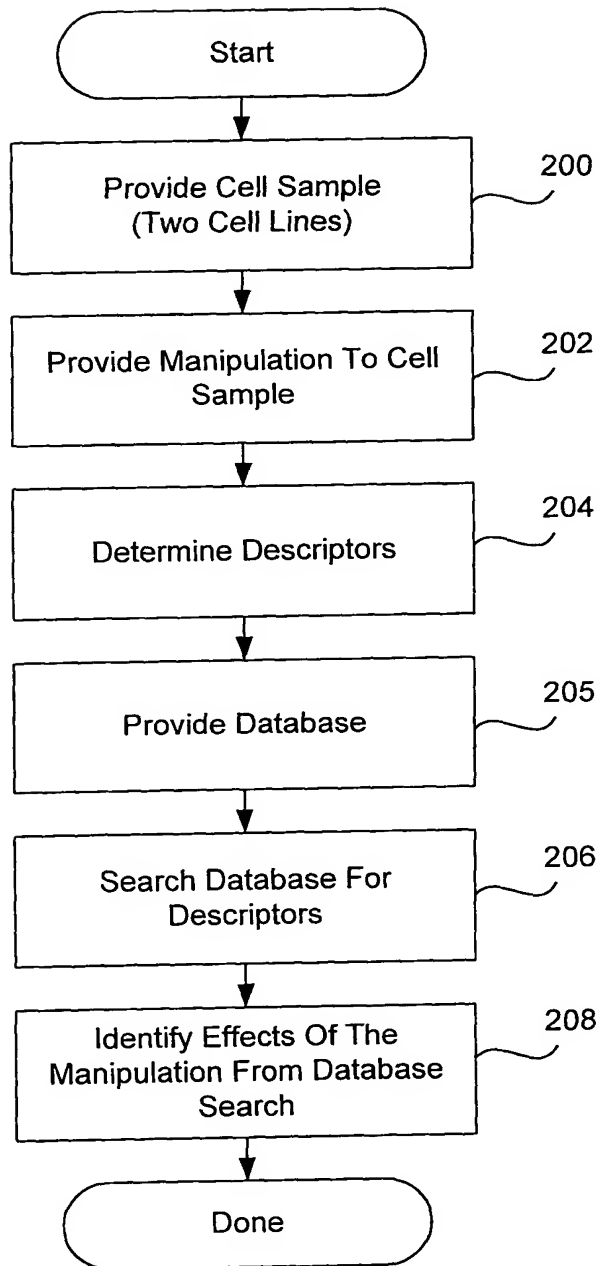
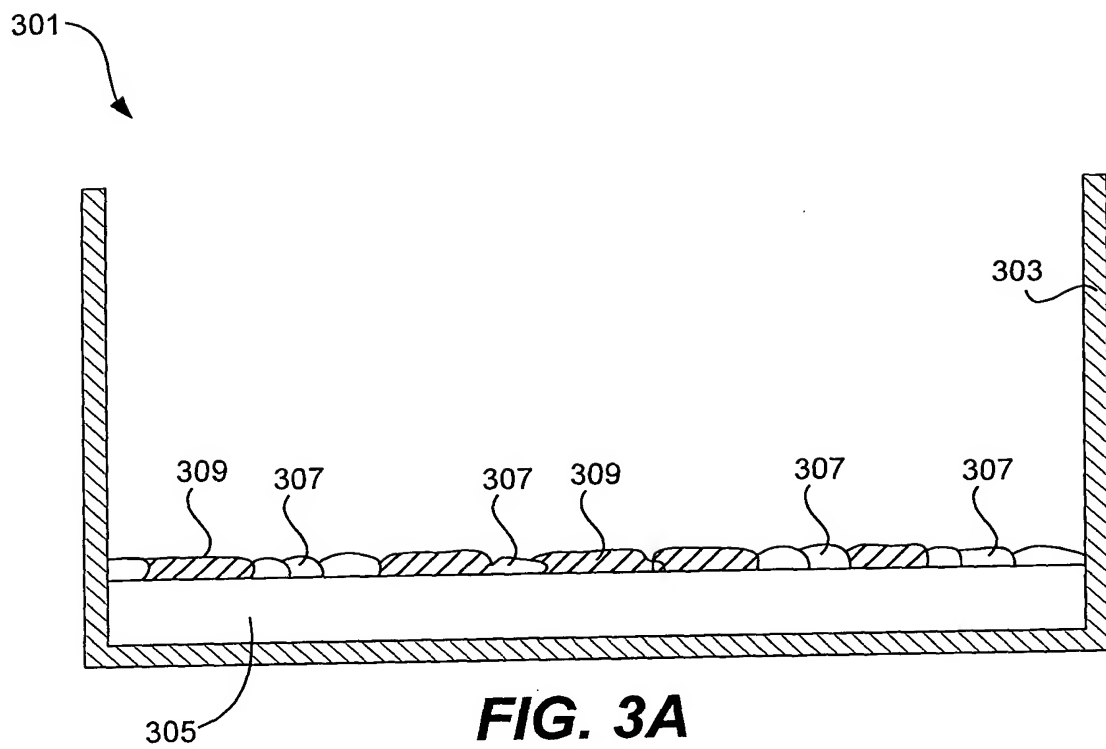


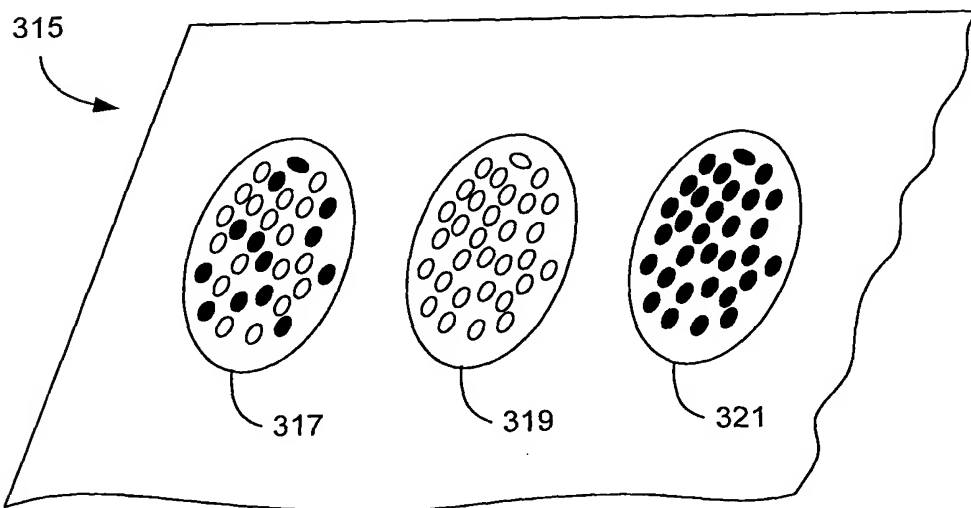
**FIG. 1**



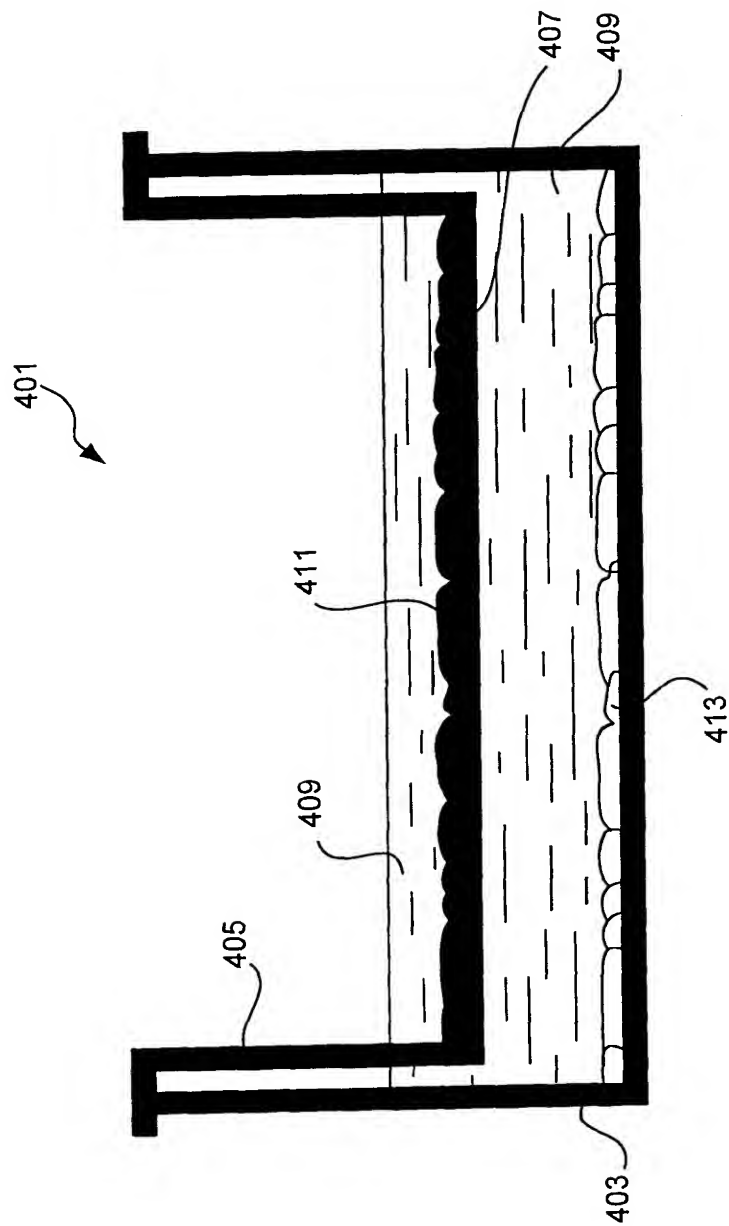
**FIG. 2**



**FIG. 3A**



**FIG. 3B**



**FIG. 4**

FIG. 5A

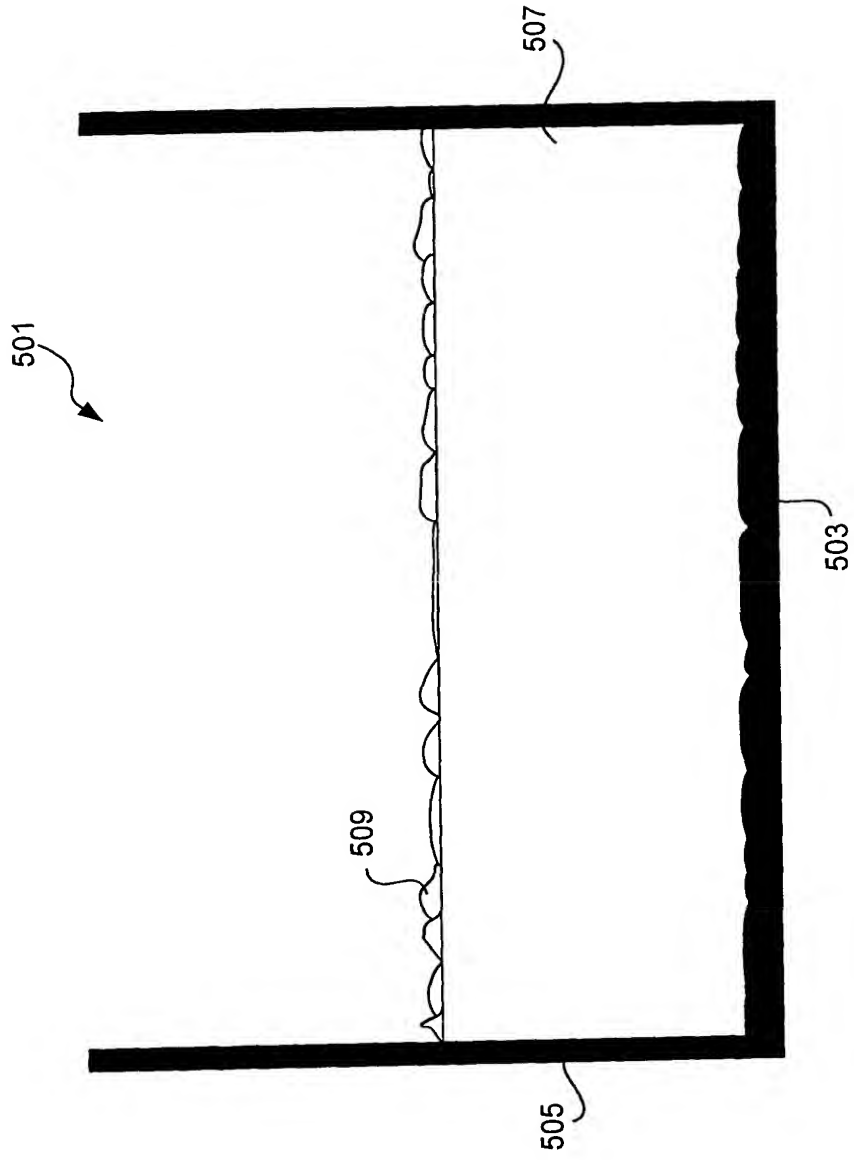
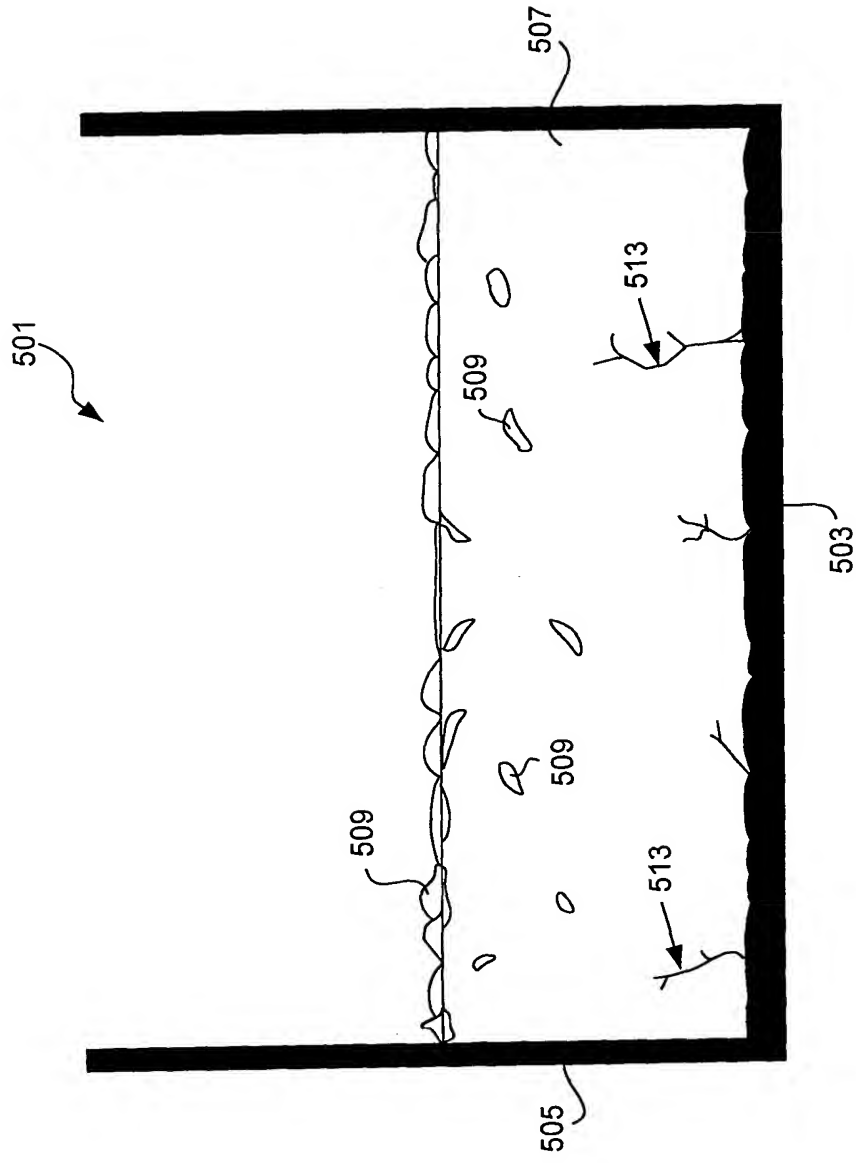
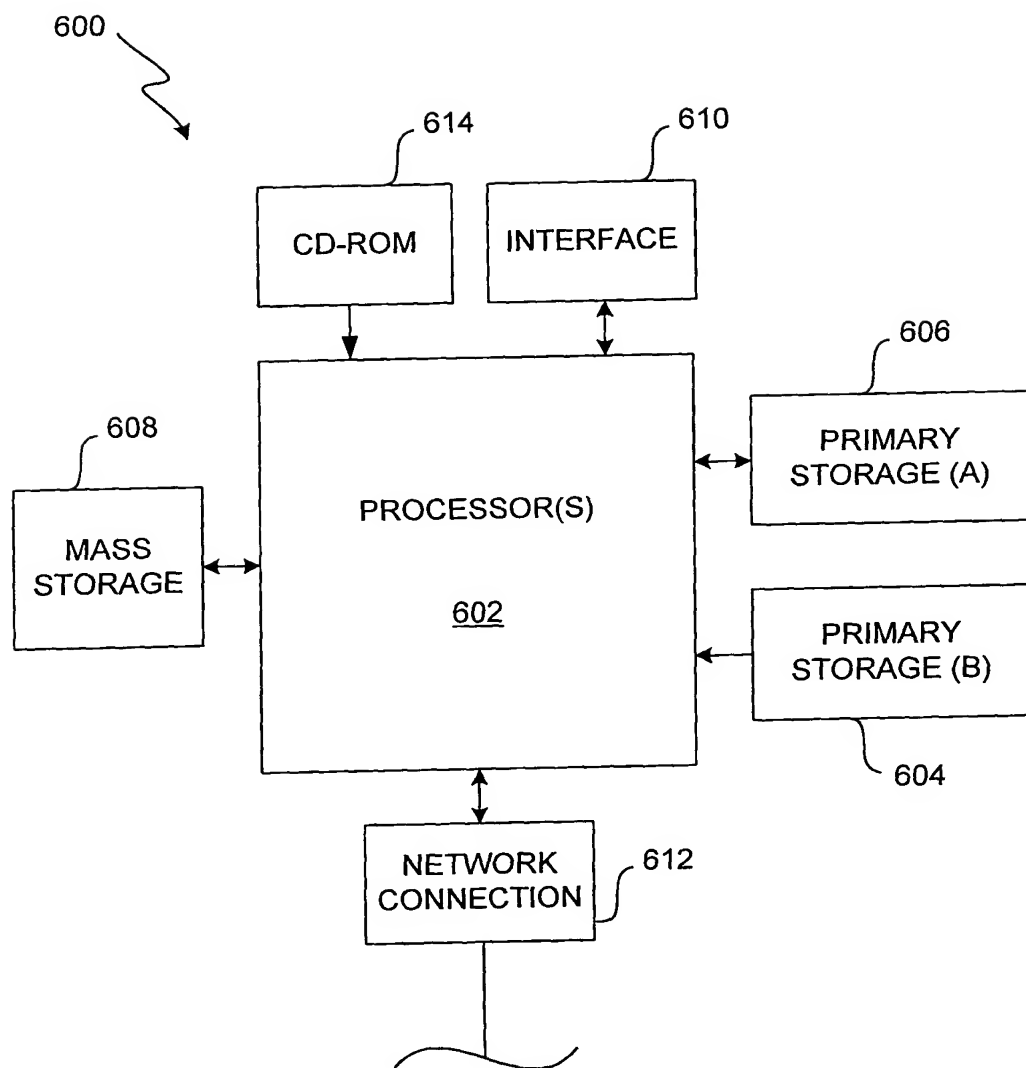


FIG. 5A

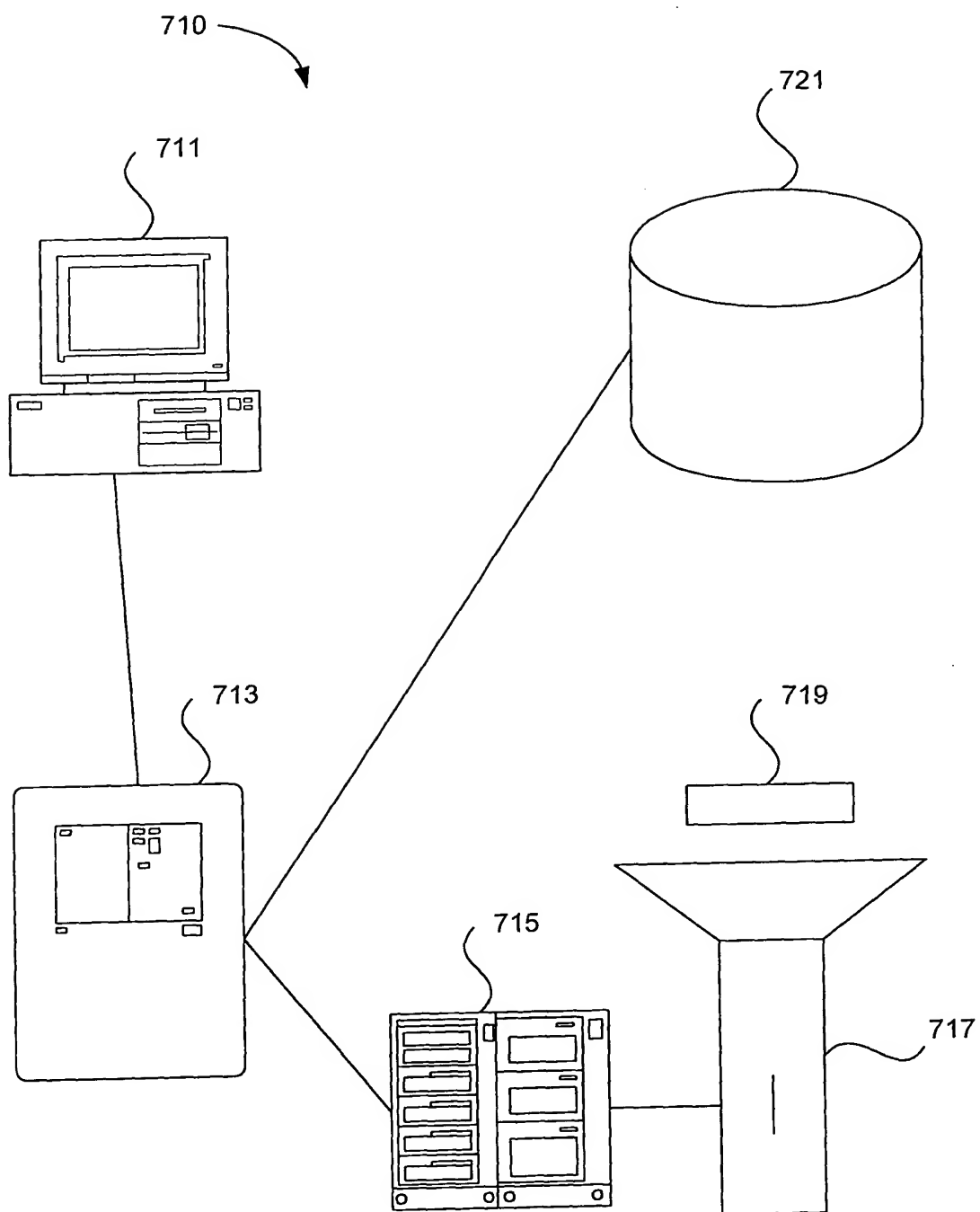
FIG. 5B is a cross-sectional view of the device 501, showing the internal structure of the device 501. The device 501 includes a top layer 503, a middle layer 505, and a bottom layer 507. The middle layer 505 is divided into two regions, 509 and 513, by a vertical line 509. The top layer 503 is divided into two regions, 509 and 513, by a vertical line 509. The bottom layer 507 is divided into two regions, 509 and 513, by a vertical line 509.



**FIG. 5B**



**FIG. 6**



**FIG. 7**